ABSTRACT

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Frame for the fabrication of electronic components, process for fabricating such components and components thus obtained

The subject of the present invention is a frame for the fabrication of electronic components, process for fabricating such components and components thus obtained.

The frame on which are formed pairs of coplanar tabs, each of which is produced as a single piece with a structural side band and extends towards another structural side band, without touching the other tab of the pair in question, characterized in that the tabs (5 and 5') of each pair are substantially aligned with each other and in that, on the one hand, one of the tabs (5) of each pair has a free end portion (6) forming an accommodating support for the semiconductor crystal (2') and in that, on the other hand, the other tab (5') of each pair has, at its free end (7), a connecting frame portion (8) which can be folded so as to come into contact with the semiconductor crystal (2') and which lies essentially within the volume defined by the planes delimiting the longitudinal edges of the said tabs (5, 5').

- Figure 6 -

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